

**DESCRIPTION**

The Teridian 73S8014RT is a single smart card (ICC) interface circuit. It is derived from the 73S8024RN industry-standard electrical interface but adds support for 1.8V smart card applications. The 73S8014RT has been optimized to match most of the typical Set-Top Box / A/V Conditional Access applications. Optimization essentially involved a smaller pin-count and support for single I/O.

The 73S8014RT has been designed to provide full electrical compliance with ISO 7816-3, EMV 4.0.

Interfacing with the system controller is done through a control bus, composed of digital inputs to control the interface, and one interrupt output to inform the system controller of the card presence and faults.

The card clock can be generated by an on-chip oscillator using an external crystal or by connection to an externally supplied clock signal. In addition, the clock divider provides divisor values of divide by 1, 2, 4 and 6.

The 73S8014RT incorporates an ISO 7816-3 activation/deactivation sequencer that controls the card signals. Level-shifters drive the card signals with the selected card voltage (1.8V, 3V or 5V), coming from an internal Low Drop-Out (LDO) voltage regulator. This LDO regulator is powered by a dedicated power supply input  $V_{PC}$ . Digital circuitry is powered separately by a digital power supply  $V_{DD}$ . With its embedded LDO regulator, the 73S8014RT is a cost-effective solution for any application where a 5V (typically -5% +10%) power supply is available.

Emergency card deactivation is initiated upon card extraction or upon any fault detected by the protection circuitry. The fault can be a card over-current,  $V_{CC}$  undervoltage or power supply fault ( $V_{DD}$ ). The card over-current circuitry is a true current detection function, as opposed to  $V_{CC}$  voltage drop detection, as usually implemented in non-Teridian 8024 interface ICs.

The  $V_{DD}$  voltage fault has a threshold voltage that can be adjusted with an external resistor network. It allows automated card deactivation at a customized  $V_{DD}$  voltage threshold value. It can be used, for instance, to match the system controller operating voltage range.

**APPLICATIONS**

- **Set-Top Box Conditional Access and Pay-per-View**
- **General purpose smart card readers**

**ADVANTAGES**

- **Same advantages as the Teridian 73S80xxR family:**
  - Card  $V_{CC}$  generated by an LDO regulator
  - Very low power dissipation (saves up to 1/2W)
  - Fewer external components are required
  - Better noise performance
- **True card over-current detection**
- **Small format 20SO package**

**FEATURES**

- **Card Interface:**
  - Complies with ISO 7816-3, EMV 4.0
  - 73S8014RT device supports 3V / 5V cards up to 65mA and 1.8V up to 40mA
  - ISO 7816-3 Activation / Deactivation sequencer
  - Automated deactivation upon hardware fault (i.e. upon drop on  $V_{DD}$  power supply or card overcurrent)
  - The  $V_{DD}$  voltage supervisor threshold value (fault) can be externally adjusted
  - Over-current detection 130mA max
  - Card CLK clock frequency up to 20MHz
- **System Controller Interface:**
  - 3 Digital inputs control the card activation / deactivation, card reset and card voltage
  - 2 Digital inputs control the card clock frequency
  - 1 Digital output, interrupt to the system controller, reports to the host the card presence and faults
  - Crystal oscillator or host clock, up to 27MHz
- **Regulator Power Supply:**
  - 4.75V to 5.5V (EMV 4.0)
- **Digital Interfacing: 2.7V to 5.5V**
- **6kV ESD protection on the card interface**
- **Package: SO 20-pin**
- **RoHS compliant (6/6) lead-free package**

FUNCTIONAL DIAGRAM

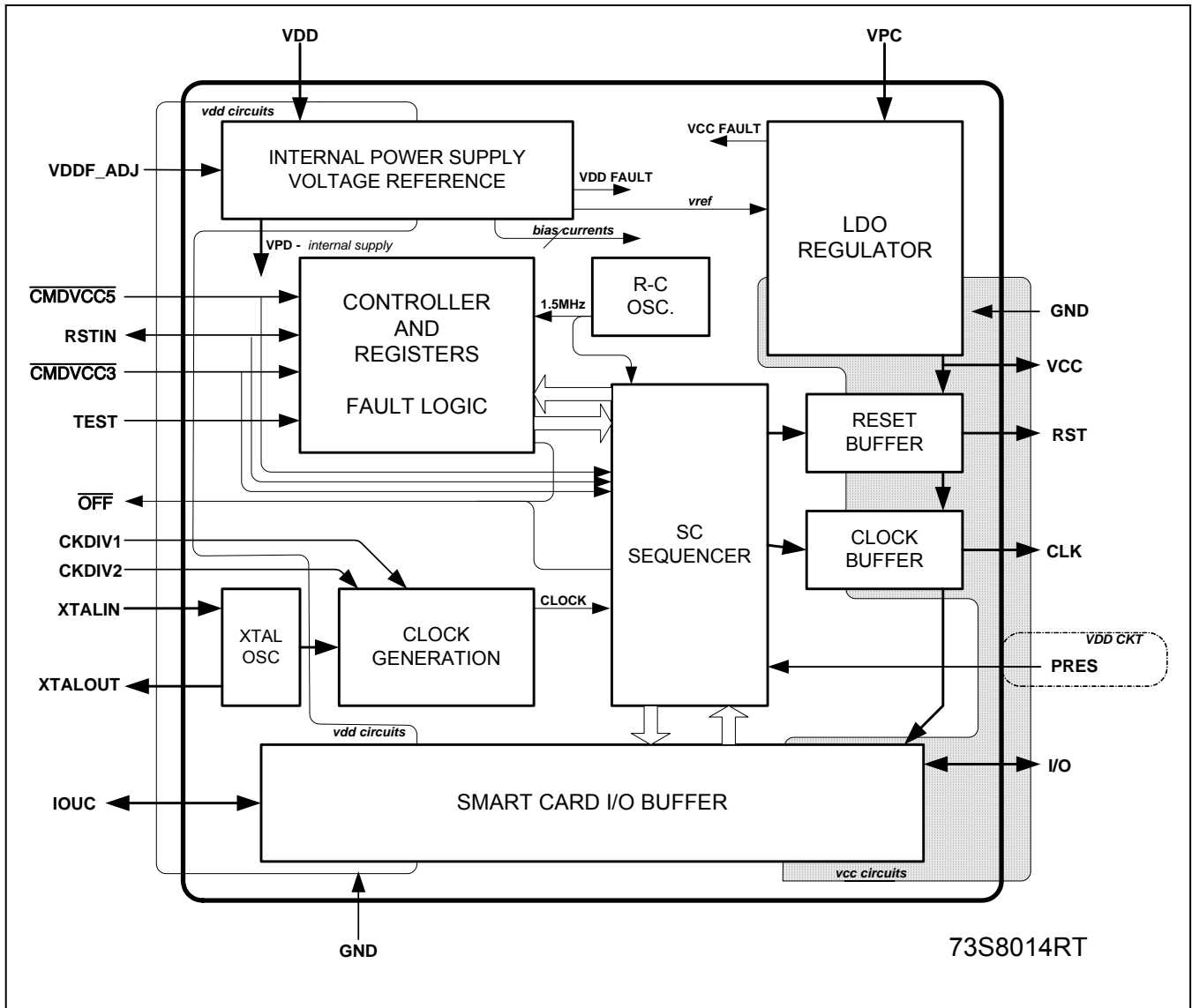


Figure 1: 73S8014RT Block Diagram

## Table of Contents

<b>1</b>	<b>Pinout .....</b>	<b>5</b>
<b>2</b>	<b>Electrical Specifications .....</b>	<b>8</b>
2.1	Absolute Maximum Ratings .....	8
2.2	Recommended Operating Conditions .....	8
2.3	Package Thermal Parameters .....	8
2.4	Smart Card Interface Requirements .....	9
2.5	Characteristics: Digital Signals.....	11
2.6	DC Characteristics .....	12
2.7	Voltage Fault Detection Circuits.....	13
<b>3</b>	<b>Applications Information .....</b>	<b>14</b>
3.1	Example 73S8014RT Schematics .....	14
3.2	System Controller Interface.....	16
3.3	Power Supply and Voltage Supervision.....	16
3.4	Card Power Supply .....	16
3.5	On-Chip Oscillator and Card Clock.....	17
3.6	Activation Sequence .....	17
3.7	Deactivation Sequence .....	19
3.8	Fault Detection and $\overline{\text{OFF}}$ .....	20
3.9	I/O Circuitry and Timing .....	20
<b>4</b>	<b>Equivalent Circuits.....</b>	<b>22</b>
<b>5</b>	<b>Mechanical Drawing.....</b>	<b>27</b>
<b>6</b>	<b>Ordering Information .....</b>	<b>28</b>
<b>7</b>	<b>Related Documentation .....</b>	<b>28</b>
<b>8</b>	<b>Contact Information .....</b>	<b>28</b>

## Figures

Figure 1: 73S8014RT Block Diagram.....	2
Figure 2: 73S8014RT 20-SOP Pin Out .....	5
Figure 3: 73S8014RT – Typical Application Schematic .....	15
Figure 4: Activation Sequence – RSTIN Low When $\overline{\text{CMDVCC5}}$ or $\overline{\text{CMDVCC3}}$ Goes Low .....	18
Figure 5: Activation Sequence – RSTIN High When $\overline{\text{CMDVCC5}}$ or $\overline{\text{CMDVCC3}}$ Goes Low .....	18
Figure 6: Deactivation Sequence .....	19
Figure 7: Timing Diagram – Management of the Interrupt Line $\overline{\text{OFF}}$ .....	20
Figure 8: I/O and I/OUC State Diagram.....	21
Figure 9: I/O – I/OUC Delays – Timing Diagram .....	21
Figure 10: Open Drain type – $\overline{\text{OFF}}$ .....	22
Figure 11: Power Input/Output Circuit, $V_{\text{DD}}$ , $V_{\text{PC}}$ , $V_{\text{CC}}$ .....	22
Figure 12: Type 5 – Smart Card CLK Driver Circuit .....	23
Figure 13: Type 6 – Smart Card RST Driver Circuit.....	23
Figure 14: Type 7A – Smart Card IO Interface Circuit .....	24
Figure 15: Type 7B – Smart Card IOUC Interface Circuit .....	24
Figure 16: Type 8 – General Input Circuit .....	25
Figure 17: Oscillator Circuit .....	25
Figure 18: $V_{\text{DD\_FLT\_ADJ}}$ .....	26
Figure 19: Mechanical Drawing 20-Pin SO Package .....	27

## Tables

Table 1: 73S8014RT 20-Pin SOP Pin Definitions .....	6
Table 2: Absolute Maximum Device Ratings.....	8
Table 3: Recommended Operating Conditions .....	8
Table 4: Package Thermal Parameters.....	8
Table 5: DC Smart Card Interface Requirements .....	9
Table 6: Digital Signals Characteristics .....	11
Table 7: DC Characteristics.....	12
Table 8: Voltage Fault Detection Circuits .....	13
Table 9: $V_{\text{CC}}$ Voltage Logic Table .....	16
Table 10: Order Numbers and Packaging Marks .....	28

## 1 Pinout

The 73S8014RT is supplied as a 20-pin SO package.

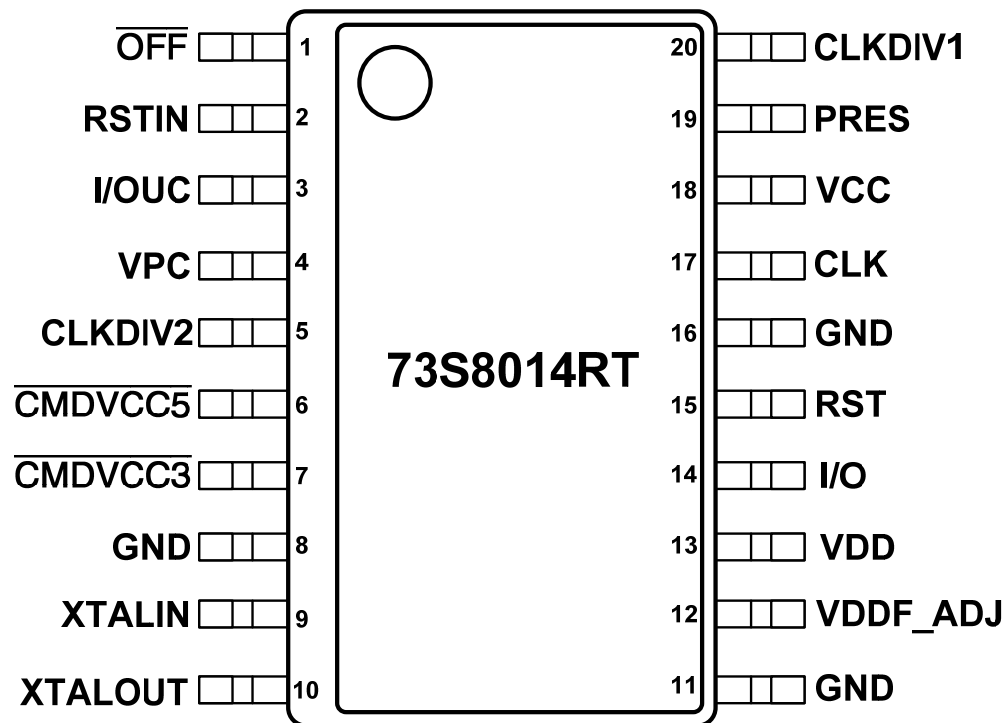


Figure 2: 73S8014RT 20-SOP Pin Out

Table 1 provides the 73S8014RT pin names, pin numbers, type, equivalent circuits and descriptions.

**Table 1: 73S8014RT 20-Pin SOP Pin Definitions**

Pin Name	Pin Number	Type	Equivalent Circuit	Description															
<b>Card Interface</b>																			
I/O	14	IO	<a href="#">Figure 14</a>	Card I/O: Data signal to/from card. Includes an 11K pull-up resistor to $V_{CC}$ .															
RST	15	O	<a href="#">Figure 13</a>	Card reset: provides reset (RST) signal to card.															
CLK	17	O	<a href="#">Figure 12</a>	Card clock: provides clock signal (CLK) to card. The rate of this clock is determined by the external crystal frequency or frequency of the external clock signal applied on XTALIN and CLKDIV selections.															
PRES	19	I	<a href="#">Figure 16</a>	Card Presence switch: active high indicates card is present. Includes a high-impedance pull-down current source.															
VCC	18	PSO	<a href="#">Figure 11</a>	Card power supply – logically controlled by sequencer, output of LDO regulator. Requires an external filter capacitor to the card GND.															
GND	16	GND	–	Card ground.															
<b>Host Processor Interface</b>																			
$\overline{\text{CMDVCC5}}$	6	I	<a href="#">Figure 16</a>	Logic low on one or both of these pins will cause the LDO regulator to ramp the Vcc supply to the smart card and smart card interface to the value described in the following table: <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th><math>\overline{\text{CMDVCC5}}</math></th> <th><math>\overline{\text{CMDVCC3}}</math></th> <th>Vcc Output Voltage</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>1.8V</td> </tr> <tr> <td>0</td> <td>1</td> <td>5.0V</td> </tr> <tr> <td>1</td> <td>0</td> <td>3.0V</td> </tr> <tr> <td>1</td> <td>1</td> <td>Vcc Off</td> </tr> </tbody> </table>	$\overline{\text{CMDVCC5}}$	$\overline{\text{CMDVCC3}}$	Vcc Output Voltage	0	0	1.8V	0	1	5.0V	1	0	3.0V	1	1	Vcc Off
$\overline{\text{CMDVCC5}}$	$\overline{\text{CMDVCC3}}$	Vcc Output Voltage																	
0	0	1.8V																	
0	1	5.0V																	
1	0	3.0V																	
1	1	Vcc Off																	
$\overline{\text{CMDVCC3}}$	7	I	<a href="#">Figure 16</a>	Note: See <a href="#">Section 3.2</a> for more details.															
CLKDIV1 CLKDIV2	20 5	I	<a href="#">Figure 16</a>	Sets the divide ratio from the XTAL oscillator (or external clock input) to the card clock. These pins include a pull-up resistor for CLKDIV1 and CLKDIV2 to provide a default rate of divide by two. <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>CLKDIV1</th> <th>CLKDIV2</th> <th>CLOCK RATE</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>XTALIN/6</td> </tr> <tr> <td>0</td> <td>1</td> <td>XTALIN/4</td> </tr> <tr> <td>1</td> <td>1</td> <td>XTALIN/2</td> </tr> <tr> <td>1</td> <td>0</td> <td>XTALIN</td> </tr> </tbody> </table>	CLKDIV1	CLKDIV2	CLOCK RATE	0	0	XTALIN/6	0	1	XTALIN/4	1	1	XTALIN/2	1	0	XTALIN
CLKDIV1	CLKDIV2	CLOCK RATE																	
0	0	XTALIN/6																	
0	1	XTALIN/4																	
1	1	XTALIN/2																	
1	0	XTALIN																	
$\overline{\text{OFF}}$	1	O	<a href="#">Figure 10</a>	Interrupt signal to the processor. Active Low – Multi-function indicating fault conditions and card presence. Open drain output configuration. It includes an internal 20k $\Omega$ pull-up to $V_{DD}$ .															
RSTIN	2	I	<a href="#">Figure 16</a>	Reset Input: This signal is the reset command to the card.															
I/OUC	3	IO	<a href="#">Figure 15</a>	System controller data I/O to/from the card. Includes an 11K pull-up resistor to $V_{DD}$ .															

<b>Miscellaneous Inputs and Outputs</b>				
XTALIN	9		<a href="#">Figure 17</a>	Crystal oscillator input: can either be connected to crystal or driven as a source for the card clock.
XTALOUT	10		<a href="#">Figure 17</a>	Crystal oscillator output: connected to crystal. Left open if XTALIN is being used as external clock input.
VDDF_ADJ	12		<a href="#">Figure 18</a>	$V_{DD}$ fault threshold adjustment input: this pin can be used to adjust the $V_{DDF}$ value (that controls deactivation of the card). Must be left open if unused.
<b>Power Supply and Ground</b>				
VDD	13	PSO	<a href="#">Figure 11</a>	System interface supply voltage and supply voltage for internal circuitry.
VPC	4	PSO	<a href="#">Figure 11</a>	LDO regulator power supply source.
GND	8, 11	GND	–	Digital ground.

## 2 Electrical Specifications

This section provides the following:

- Absolute maximum ratings
- Recommended operating conditions
- Package thermal parameters
- Smart card interface requirements
- Digital signals characteristics
- DC Characteristics
- Voltage Fault Detection Circuits

### 2.1 Absolute Maximum Ratings

Table 2 lists the maximum operating conditions for the 73S8014RT. Permanent device damage may occur if absolute maximum ratings are exceeded. Exposure to the extremes of the absolute maximum rating for extended periods may affect device reliability. The smart card interface pins are protected against short circuits to  $V_{CC}$ , ground, and each other.

**Table 2: Absolute Maximum Device Ratings**

Parameter	Rating
Supply Voltage $V_{DD}$	-0.5 to 6.0 VDC
Supply Voltage $V_{PC}$	-0.5 to 6.0 VDC
Input Voltage for Digital Inputs	-0.3 to ( $V_{DD} + 0.5$ ) VDC
Storage Temperature	-60 to 150°C
Pin Voltage (except card interface)	-0.3 to ( $V_{DD} + 0.5$ ) VDC
Pin Voltage (card interface)	-0.3 to ( $V_{CC} + 0.5$ ) VDC
ESD Tolerance – Card interface pins	+/- 6kV
ESD Tolerance – Other pins	+/- 2kV

\* Note: ESD testing on smart card pins is HBM condition, 3 pulses, each polarity referenced to ground.

Note: Smart Card pins are protected against shorts between any combinations of Smart Card pins.

### 2.2 Recommended Operating Conditions

Function operation should be restricted to the recommended operating conditions specified in Table 3.

**Table 3: Recommended Operating Conditions**

Parameter	Rating
Supply Voltage $V_{DD}$	2.7 to 5.5 VDC
Supply Voltage $V_{PC}$	4.75 to 5.5 VDC
Ambient Operating Temperature	-40°C to +85°C
Input Voltage for Digital Inputs	0V to $V_{DD} + 0.3V$

### 2.3 Package Thermal Parameters

Table 4 lists the 73S8014RT Smart Card package thermal parameters.

**Table 4: Package Thermal Parameters**

Parameter	Rating
20 SO	50°C / W



## 2.4 Smart Card Interface Requirements

Table 5 lists the 73S8014RT Smart Card interface requirements.

**Table 5: DC Smart Card Interface Requirements**

Symbol	Parameter	Condition	Min	Nom	Max	Unit
<b>Card Power Supply (<math>V_{CC}</math>) Regulator</b>						
<b>General conditions, <math>-40^{\circ}\text{C} &lt; T &lt; 85^{\circ}\text{C}</math>, <math>4.75\text{V} &lt; V_{PC} &lt; 5.5\text{V}</math>, <math>2.7\text{V} &lt; V_{DD} &lt; 5.5\text{V}</math></b>						
$V_{CC}$	Card supply voltage including ripple and noise	Inactive mode	-0.1		0.1	V
		Inactive mode, $I_{CC} = 1\text{mA}$	-0.1		0.4	V
		Active mode; $I_{CC} < 65\text{mA}$ ; 5V	4.65		5.25	V
		Active mode; $I_{CC} < 65\text{mA}$ ; 3V	2.85		3.15	V
		Active mode; $I_{CC} < 40\text{mA}$ ; 1.8V	1.68		1.92	V
		Active mode; single pulse of 100mA for 2 $\mu\text{s}$ ; 5V, fixed load = 25mA	4.6		5.25	V
		Active mode; single pulse of 100mA for 2 $\mu\text{s}$ ; 3V, fixed load = 25mA	2.76		3.2	V
		Active mode; current pulses of 40nAs with peak $ I_{CC}  < 200\text{mA}$ , $t < 400\text{ns}$ ; 5V	4.6		5.25	V
		Active mode; current pulses of 40nAs with peak $ I_{CC}  < 200\text{mA}$ , $t < 400\text{ns}$ ; 3V	2.76		3.15	V
		Active mode; current pulses of 20nAs with peak $ I_{CC}  < 100\text{mA}$ , $t < 400\text{ns}$ ; 1.8V <sup>(1)</sup>	1.62		1.92	V
$V_{CCrip}$	$V_{CC}$ Ripple	$f_{RIPPLE} = 20\text{K} - 200\text{MHz}$			350	mV
$I_{CCmax}$	Card supply output current	Static load current, $V_{CC} > 4.6$ or 2.7 volts as selected	65			mA
		Static load current, $V_{CC} > 1.62$	40			mA
$I_{CCF}$	$I_{CC}$ fault current		70		130	mA
$V_{SR}$	$V_{CC}$ slew rate, rise	$C_F = 1.0\mu\text{F}$ on $V_{CC}$	0.06	0.150	0.30	V/ $\mu\text{s}$
$V_{SF}$	$V_{CC}$ slew rate, fall	$C_F = 1.0\mu\text{F}$ on $V_{CC}$	0.075	0.150	0.60	V/ $\mu\text{s}$
$C_F$	External filter cap ( $V_{CC}$ to GND)	$C_F$ should be ceramic with low ESR (<100m $\Omega$ ).	0.5	1.0	1.5	$\mu\text{F}$

Symbol	Parameter	Condition	Min	Nom	Max	Unit
<b>Interface Requirements – Data Signals: I/O and Host Interfaces: I/OUC.</b>						
<b>I<sub>SHORTL</sub>, I<sub>SHORTH</sub>, and V<sub>INACT</sub> requirements do not pertain to I/OUC.</b>						
V <sub>OH</sub>	Output level, high (I/OUC)	I <sub>OH</sub> = 0	0.9 V <sub>DD</sub>		V <sub>DD</sub> +0.1	V
		I <sub>OH</sub> = -40μA	0.75 V <sub>DD</sub>		V <sub>DD</sub> +0.1	V
	Output level, high (I/O)	I <sub>OH</sub> = 0	0.9 V <sub>CC</sub>		V <sub>CC</sub> +0.1	V
		I <sub>OH</sub> = -40μA (V <sub>CC</sub> = 3/5V), I <sub>OH</sub> = -20μA (V <sub>CC</sub> = 1.8V)	0.75 V <sub>CC</sub>		V <sub>CC</sub> +0.1	V
V <sub>OL</sub>	Output level, low (I/OUC)	I <sub>OL</sub> = 1mA			0.3	V
	Output level, low (I/O)	V <sub>CC</sub> = 5V			0.45	V
		V <sub>CC</sub> = 3V			0.2	V
		V <sub>CC</sub> = 1.8V			0.15 V <sub>CC</sub>	V
V <sub>IH</sub>	Input level, high		1.8		V <sub>DD</sub> + 0.3	V
	Input level, high (I/O)		0.6 V <sub>CC</sub>		V <sub>CC</sub> +0.30	V
V <sub>IL</sub>	Input level, low		-0.3		0.8	V
	Input level, low (I/O)	V <sub>CC</sub> = 5V, 3V	-0.3		0.8	V
		V <sub>CC</sub> = 1.8V	-0.3		0.2 V <sub>CC</sub>	V
V <sub>INACT</sub>	Output voltage when outside of session	I <sub>OL</sub> = 0			0.1	V
		I <sub>OL</sub> = 1mA			0.3	V
I <sub>LEAK</sub>	Input leakage	V <sub>IH</sub> = V <sub>CC</sub>			10	μA
I <sub>IL</sub>	Input current, low	V <sub>IL</sub> = 0			0.65	mA
I <sub>SHORTL</sub>	Short circuit output current	For output low, shorted to V <sub>CC</sub> through 33 Ω			15	mA
I <sub>SHORTH</sub>	Short circuit output current	For output high, shorted to ground through 33 Ω			15	mA
t <sub>R</sub> , t <sub>F</sub>	Output rise time, fall times	C <sub>L</sub> = 80pF, 10% to 90%.			100	ns
t <sub>IR</sub> , t <sub>IF</sub>	Input rise, fall times				1	μs
R <sub>PU</sub>	Internal pull-up resistor	Output stable for >400ns	8	11	14	kΩ
FD <sub>MAX</sub>	Maximum data rate				1	MHz
T <sub>FDIO</sub>	Delay, I/O to I/OUC, I/OUC to I/O, (respectively falling edge to falling edge and rising edge to rising edge)	Edge from master to slave, measured at 50%	60	100	200	ns
T <sub>RDIO</sub>				15		ns
C <sub>IN</sub>	Input capacitance				10	pF

Symbol	Parameter	Condition	Min	Nom	Max	Unit
<b>Reset and Clock for Card Interface, RST, CLK</b>						
V <sub>OH</sub>	Output level, high	I <sub>OH</sub> = -200μA	0.9 V <sub>CC</sub>		V <sub>CC</sub>	V
V <sub>OL</sub>	Output level, low	I <sub>OL</sub> = 200μA, V <sub>CC</sub> = 5V	0		0.45	V
		I <sub>OL</sub> = 200μA, V <sub>CC</sub> = 3V	0		0.2	V
		I <sub>OL</sub> = 200μA, V <sub>CC</sub> = 1.8V	0		0.15 V <sub>CC</sub>	V
V <sub>INACT</sub>	Output voltage when outside of session	I <sub>OL</sub> = 0			0.1	V
		I <sub>OL</sub> = 1mA			0.3	V
I <sub>RST_LIM</sub>	Output current limit, RST				30	mA
I <sub>CLK_LIM</sub>	Output current limit, CLK				70	mA
CLK <sub>SR3V</sub>	CLK slew rate	<	0.3			V/ns
CLK <sub>SR5V</sub>	CLK slew rate	V <sub>CC</sub> = 5V	0.5			V/ns
t <sub>R</sub> , t <sub>F</sub>	Output rise time, fall time	C <sub>L</sub> = 35pF for CLK, 10% to 90%			8	ns
		C <sub>L</sub> = 200pF for RST, 10% to 90%			100	ns
δ	Duty cycle for CLK	C <sub>L</sub> = 35pF, F <sub>CLK</sub> ≤ 20MHz C <sub>L</sub> = 35pF, F <sub>CLK</sub> < 10MHz V <sub>CC</sub> = 1.8V	45		55	%

## 2.5 Characteristics: Digital Signals

Table 6 lists the 73S8014RT digital signals characteristics.

**Table 6: Digital Signals Characteristics**

Symbol	Parameter	Condition	Min	Nom	Max	Unit
<b>Digital I/O Except for XTALIN and XTALOUT</b>						
V <sub>IL</sub>	Input Low Voltage		-0.3		0.8	V
V <sub>IH</sub>	Input High Voltage		1.8		V <sub>DD</sub> + 0.3	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2mA			0.45	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -1mA	V <sub>DD</sub> - 0.45			V
R <sub>OUT</sub>	Pull-up resistor, $\overline{\text{OFF}}$		16	20	24	kΩ
I <sub>IL1</sub>	Input Leakage Current	GND < V <sub>IN</sub> < V <sub>DD</sub>	-5		5	μA
I <sub>IL2</sub>	Input Leakage Current	GND < V <sub>IN</sub> < V <sub>DD</sub> CLKDIV2 only	-15		15	μA

Oscillator (XTALIN) I/O Parameters						
$V_{ILXTAL}$	Input Low Voltage - XTALIN		-0.3		$0.3 V_{DD}$	V
$V_{IHXTAL}$	Input High Voltage - XTALIN		$0.7 V_{DD}$		$V_{DD}+0.3$	V
$I_{ILXTAL}$	Input Current - XTALIN	$GND < V_{IN} < V_{DD}$	-30		30	$\mu A$
$f_{MAX}$	Max freq. Osc or external clock				27	MHz
$\delta_{in}$	External input duty cycle limit	$t_{R/F} < 10\% f_{IN}$ , $45\% < \delta_{CLK} < 55\%$	48		52	%

## 2.6 DC Characteristics

Table 7 lists the 73S8014RT DC characteristics.

**Table 7: DC Characteristics**

Symbol	Parameter	Condition	Min	Nom	Max	Unit
$I_{DD}$	Supply Current	12 MHz XTAL		2.7	7.0	mA
		Ext CLK, $V_{DD} = 2.7 - 3.6V$ , $V_{CC}$ Off		1.7		mA
		Ext CLK, $V_{DD} = 2.7 - 3.6V$ , $V_{CC}$ On		2.2		mA
		Ext CLK, $V_{DD} = 4.5 - 5.5V$ , $V_{CC}$ Off		2.7		mA
		Ext CLK, $V_{DD} = 4.5 - 5.5V$ , $V_{CC}$ On		3		mA
$I_{PC}$	Supply Current	$V_{CC}$ on, $I_{CC}=0$ I/O, AUX1, AUX2=high, Clock not toggling		450	700	$\mu A$
$I_{PCOFF}$	$V_{PC}$ supply current when $V_{CC} = 0$	$\overline{CMDVCC5}$ or $\overline{CMDVCC3}$ High		345	650	$\mu A$

## 2.7 Voltage Fault Detection Circuits

Table 8 lists the 73S8014RT Voltage Fault Detection Circuits.

**Table 8: Voltage Fault Detection Circuits**

Symbol	Parameter	Condition	Min	Nom	Max	Unit
$V_{DDF}$	$V_{DD}$ fault ( $V_{DD}$ Voltage supervisor threshold)	No external resistor on $V_{DDF\_ADJ}$ pin	2.15		2.4	V
$V_{CCF}$	$V_{CC}$ fault ( $V_{CC}$ Voltage supervisor threshold)	$V_{CC} = 5v$			4.6	V
		$V_{CC} = 3v$			2.7	V

### 3 Applications Information

This section provides general usage information for the design and implementation of the 73S8014RT. The documents listed in [Related Documentation](#) provide more detailed information.

#### 3.1 Example 73S8014RT Schematics

Figure 3 shows a typical application schematic for the implementation of the 73S8014RT.



### 3.2 System Controller Interface

Three digital inputs allow direct control of the card interface by the host.

The 73S8014RT is controlled as follows:

- Pins  $\overline{\text{CMDVCC5}}$  and/or  $\overline{\text{CMDVCC3}}$ : When low, starts an activation sequence at the voltage specified in Table 9.
- Pin RSTIN: controls the card RST signal (when enabled by the sequencer)

**Table 9: V<sub>CC</sub> Voltage Logic Table**

Control Pins		V <sub>CC</sub> Voltage	Notes
$\overline{\text{CMDVCC5}}$	$\overline{\text{CMDVCC3}}$		
1	1	0V	Off
0	1	5V	
1	0	3V	
0	0	1.8V	Must be asserted within 400ns of each other to generate 1.8V

Card clock frequency can be controlled by 2 digital inputs:

- CLKDIV1 and CLKDIV2 define the division rate for the clock frequency, from the input clock frequency (crystal or external clock)

Interrupt output to the host: As long as the card is not activated, the  $\overline{\text{OFF}}$  pin informs the host about the card presence only (Low = No card in the reader). When  $\overline{\text{CMDVCC5}}$  or  $\overline{\text{CMDVCC3}}$  is asserted low (Card activation sequence requested from the host), low level on  $\overline{\text{OFF}}$  means a fault has been detected (e.g. card removal during card session, voltage fault, or over-current fault) that automatically initiates a deactivation sequence.

### 3.3 Power Supply and Voltage Supervision

The Teridian 73S8014RT smart card interface ICs incorporate an LDO voltage regulator. The voltage output is controlled by both the  $\overline{\text{CMDVCC5}}$  and  $\overline{\text{CMDVCC3}}$  pins. This regulator is able to provide either 3V or 5V or 1.8V card voltage from the power supply applied on the VPC pin. The voltage regulator can provide a current of at least 65mA on VCC for both 3V and 5V that complies with EMV 4.0.

Digital circuitry is powered by the power supply applied on the VDD pin. V<sub>DD</sub> also defines the voltage range to interface with the system controller. A card deactivation sequence is forced upon fault of any of this voltage supervisor. One voltage supervisor constantly monitors the V<sub>DD</sub> voltage. It is used to initialize the ISO-7816-3 sequencer at power-on, and to deactivate the card at power-off or upon fault. The voltage threshold of the V<sub>DD</sub> voltage supervisor is internally set by default to 2.26V nominal. However, it may be desirable, in some applications, to modify this threshold value.

The method of adjusting the V<sub>DD</sub> fault voltage is to use a resistive network of R3 from the VDDF\_ADJ pin to V<sub>DD</sub> supply and R1 from the VDDF\_ADJ pin to ground (see application schematics). In order to set the new threshold voltage, the equivalent voltage divider ratio must be determined. This ratio value will be designated Kx. Kx is defined as  $R1/(R1+R3)$ . Kx is calculated as:

$$Kx = (2.71 / V_{TH}) - 0.595 \text{ where } V_{TH} \text{ is the desired new threshold voltage.}$$

To determine the values of R1 and R3, use the following formulas (the parallel resistance of R1 and R3 is selected to be 24000 ohms)

$$R3 = 24000 / Kx \quad R1 = R3 * (Kx / (1 - Kx))$$

Taking the example above, where a V<sub>DD</sub> fault threshold voltage of 2.6V is desired, solving for Kx gives:

$$\rightarrow Kx = (2.71 / 2.6) - 0.595 = 0.4473.$$

$$\text{Solving for R3 gives: } \rightarrow R3 = 24000 / 0.4473 = 53654.$$

$$\text{Solving for R1 gives: } \rightarrow R1 = 58752 * (0.4473 / (1 - 0.4473)) = 43422.$$

Using standard 1 % resistor values gives R3 = 53.6K $\Omega$  and R1 = 43.2K $\Omega$ .



Using 1% external resistors and a parallel resistance of 24K ohms will result in a +/- 6% tolerance in the value of VDD Fault. The sources of variation due to integrated circuit process variations and mismatches include the internal reference voltage (less than +/- 1%), the internal comparator hysteresis and offset (less than +/- 1.7% for part-to-part, processing and environment), the internal resistor value mismatch and value variations (less than 1.8%), and the external resistor values (1%).

If the 2.26V default threshold is used, this pin must be left unconnected.

### 3.4 Card Power Supply

The card power supply is internally provided by the LDO regulator and controlled by the digital ISO-7816-3 sequencer. Card voltage selection on the 73S8014RT is carried out by the digital inputs CMDVCC5 and CMDVCC3.

### 3.5 On-Chip Oscillator and Card Clock

The 73S8014RT devices have an on-chip oscillator that can generate the smart card clock using an external crystal (connected between the pins XTALIN and XTALOUT) to set the oscillator frequency. When the clock signal is available from another source, it can be connected to the pin XTALIN, and the pin XTALOUT should be left unconnected.

The card clock frequency may be chosen between 4 different division rates, defined by digital inputs CLKDIV 1 and CLKDIV 2, as per the following table:

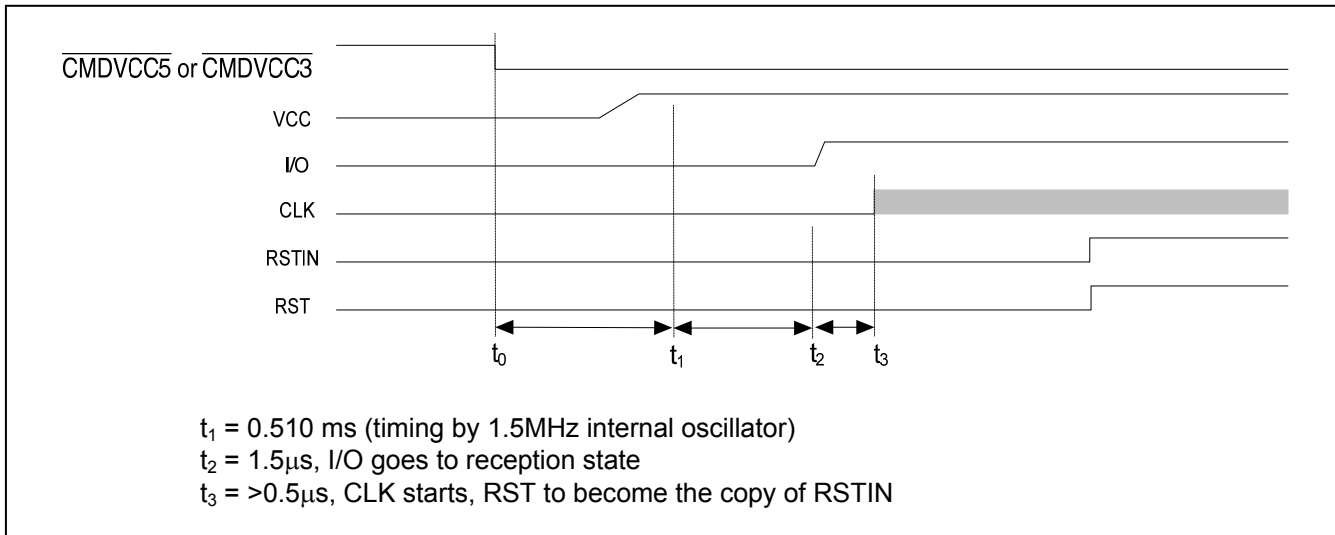
CLKDIV1	CLKDIV2	CLK	Max XTALIN
0	0	1/6 XTALIN	27MHz
0	1	1/4 XTALIN	27MHz
1	0	XTALIN	20MHz
1	1	1/2 XTALIN	27MHz

### 3.6 Activation Sequence

The 73S8014RT smart card interface ICs have an internal 10ms delay on the application of VDD where  $V_{DD} > V_{DDF}$ . No activation is allowed during this 10ms period. The CMDVCC% or CMDVCC# (edge triggered) signals must then be set low to activate the card. In order to initiate activation, the card must be present; there can be no VDD fault.

The following steps show the activation sequence and the timing of the card control signals when the system controller sets CMDVCC% or CMDVCC# low while the RSTIN is low:

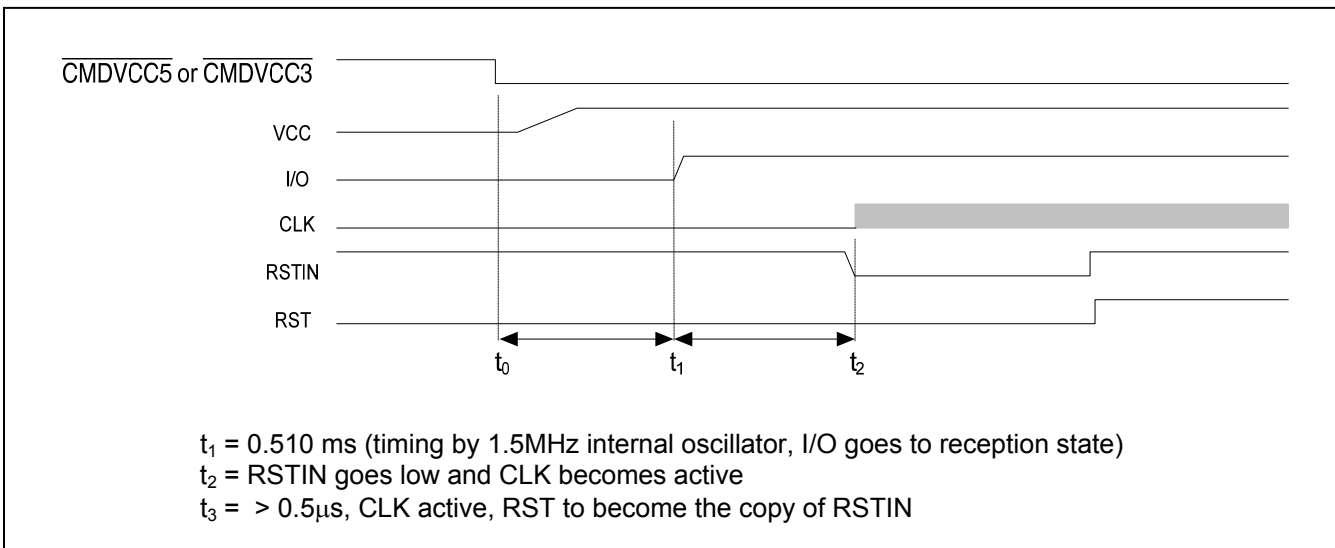
- CMDVCC% or CMDVCC# is set low at  $t_0$ .
- VCC will rise to the selected level and then the internal VCC control circuit checks the presence of VCC at the end of  $t_1$ . In normal operation, the voltage VCC to the card becomes valid before  $t_1$ . If VCC is not valid at  $t_1$ , the OFF goes low to report a fault to the system controller, and VCC to the card is shut off.
- Turn I/O to reception mode at  $t_2$ .
- CLK is applied to the card at  $t_3$ .
- RST is a copy of RSTIN after  $t_3$ .



**Figure 4: Activation Sequence – RSTIN Low When  $\overline{\text{CMDVCC5}}$  or  $\overline{\text{CMDVCC3}}$  Goes Low**

The following steps show the activation sequence and the timing of the card control signals when the system controller pulls  $\overline{\text{CMDVCC\%}}$  or  $\overline{\text{CMDVCC\#}}$  low while the RSTIN is high:

- $\overline{\text{CMDVCC\%}}$  or  $\overline{\text{CMDVCC\#}}$  is set low at  $t_0$ .
- VCC will rise to the selected level and then the internal  $V_{CC}$  control circuit checks the presence of VCC at the end of  $t_1$ . In normal operation, the voltage  $V_{CC}$  to the card becomes valid before  $t_1$ . If VCC is not valid at  $t_1$ , the OFF goes low to report a fault to the system controller, and  $V_{CC}$  to the card is shut off.
- At the fall of RSTIN at  $t_2$ , CLK is applied to the card
- RST is a copy of RSTIN after  $t_2$ .



**Figure 5: Activation Sequence – RSTIN High When  $\overline{\text{CMDVCC5}}$  or  $\overline{\text{CMDVCC3}}$  Goes Low**

### 3.7 Deactivation Sequence

Deactivation is initiated either by the system controller by setting CMDVCC% and CMDVCC# high, or automatically in the event of hardware faults. Hardware faults are over-current, V<sub>DD</sub> fault, V<sub>CC</sub> fault, and card extraction during the session.

The following steps show the deactivation sequence and the timing of the card control signals when the system controller sets CMDVCC% and CMDVCC# high or OFF goes low due to a fault or card removal:

- RST goes low at the end of t<sub>1</sub>.
- CLK is set low at the end of t<sub>2</sub>.
- I/O goes low at the end of t<sub>3</sub>. Out of reception mode.
- V<sub>CC</sub> is shut down at the end of time t<sub>4</sub>. After a delay t<sub>5</sub> (discharge of the V<sub>CC</sub> capacitor), V<sub>CC</sub> is low.

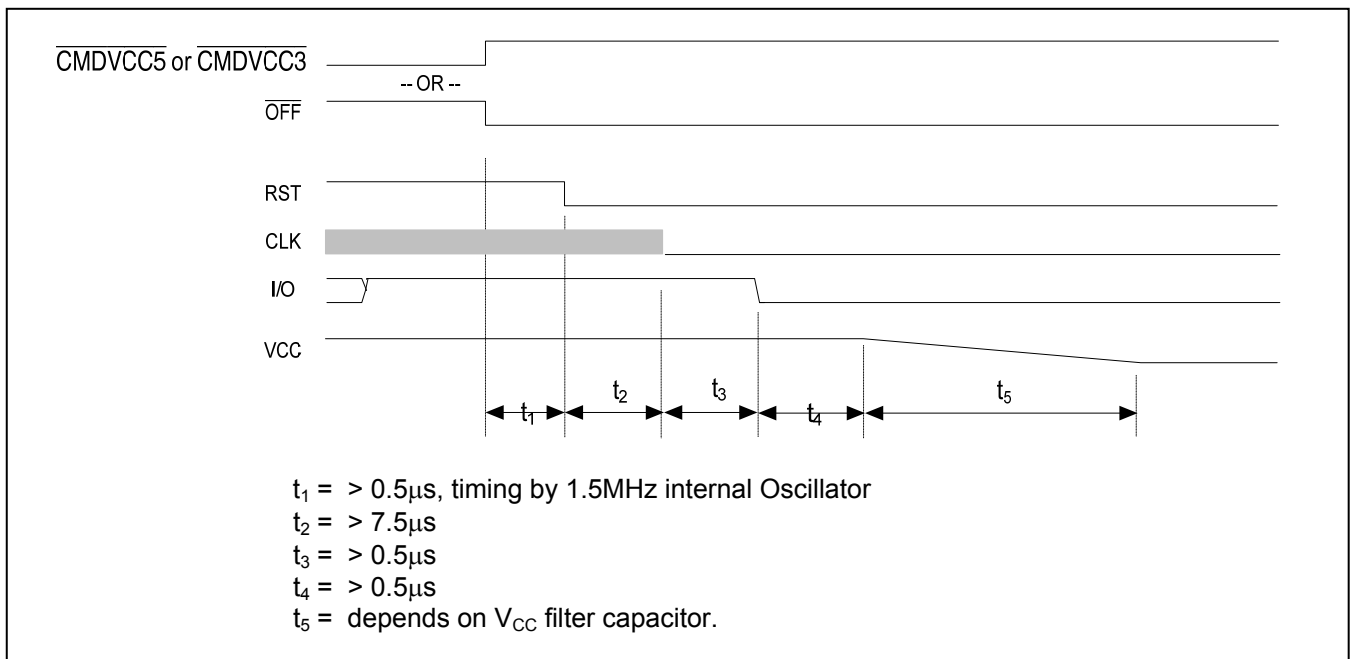


Figure 6: Deactivation Sequence

### 3.8 Fault Detection and $\overline{\text{OFF}}$

There are two different cases that the system controller can monitor the  $\overline{\text{OFF}}$  signal: to query regarding the card presence outside card sessions, or for fault detection during card sessions.

Outside a card session: In this condition,  $\overline{\text{CMDVCC5}}$  and  $\overline{\text{CMDVCC3}}$  are always high,  $\overline{\text{OFF}}$  is low if the card is not present, and high if the card is present. Because it is outside a card session, any fault detection will not act upon the  $\overline{\text{OFF}}$  signal. No deactivation is required during this time.

During a card session:  $\overline{\text{CMDVCC5}}$  or  $\overline{\text{CMDVCC3}}$  is/are always low, and  $\overline{\text{OFF}}$  falls low if the card is extracted or if any fault detection is detected. At the same time that  $\overline{\text{OFF}}$  is set low, the sequencer starts the deactivation process.

Figure 7 shows the timing diagram for the signals  $\overline{\text{CMDVCC5}}$  or  $\overline{\text{CMDVCC3}}$ , PRES, and  $\overline{\text{OFF}}$  during a card session and outside the card session:

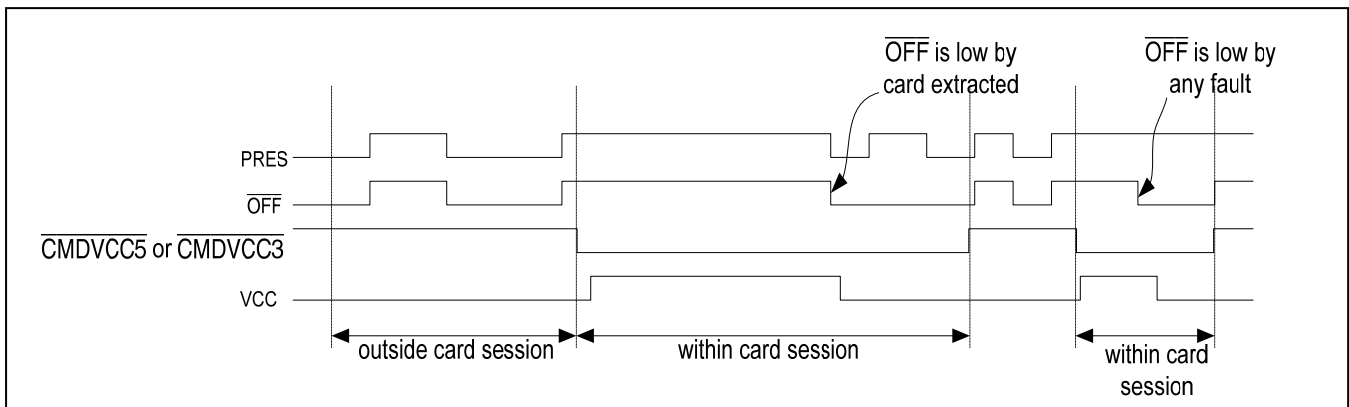


Figure 7: Timing Diagram – Management of the Interrupt Line  $\overline{\text{OFF}}$

### 3.9 I/O Circuitry and Timing

The state of the I/O pin is low after power on reset and it goes high when the activation sequencer turns on the I/O reception state. See the [Activation Sequence](#) section for details on when the I/O reception is enabled. The state of I/OUC is high after power on reset.

Within a card session and when the I/O reception state is turned on, the first I/O line on which a falling edge is detected becomes the input I/O line and the other becomes the output I/O line. When the input I/O line rising edge is detected then both I/O lines return to their neutral state.

Figure 8 shows the state diagram of how the I/O and I/OUC lines are managed to become input or output. The delay between the I/O signals is shown in Figure 9.

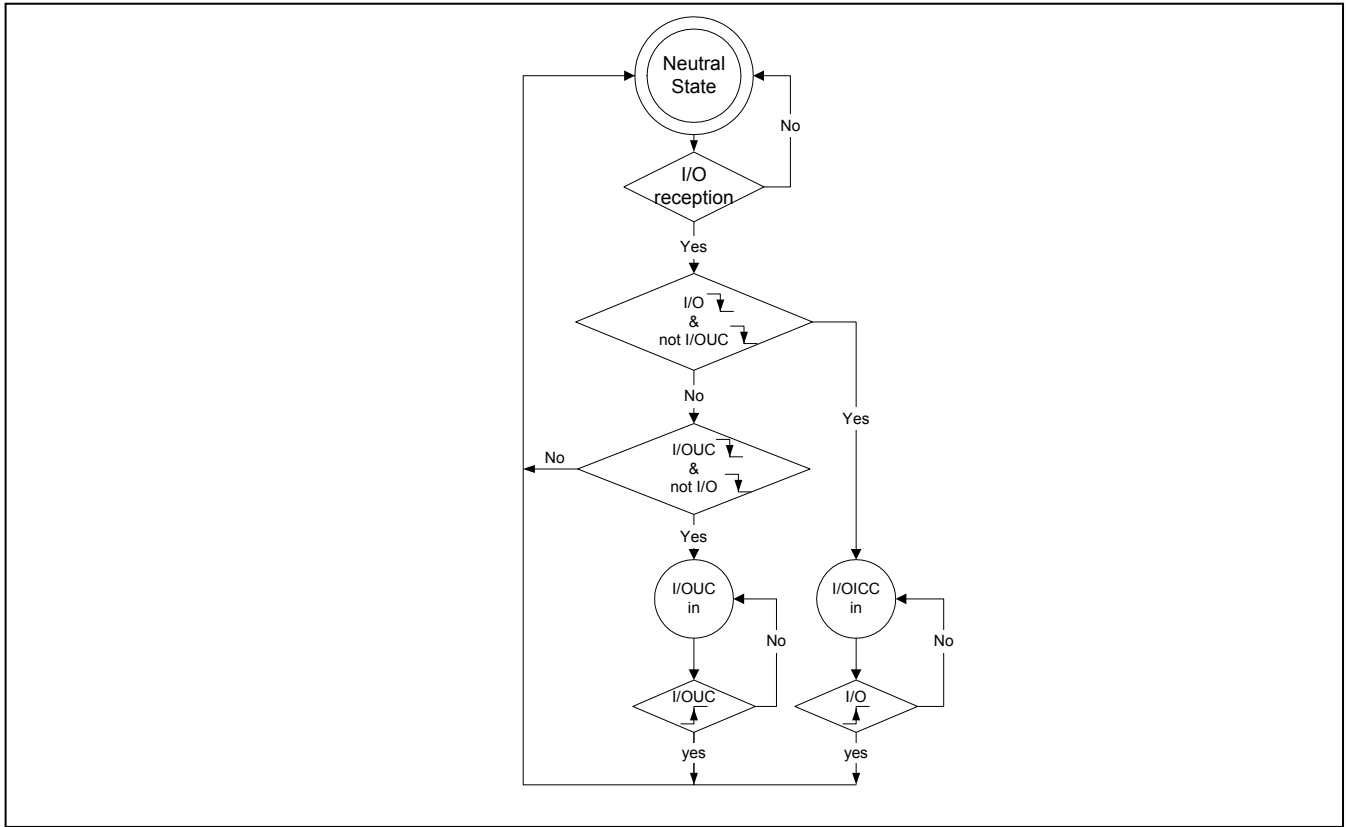


Figure 8: I/O and I/OUC State Diagram

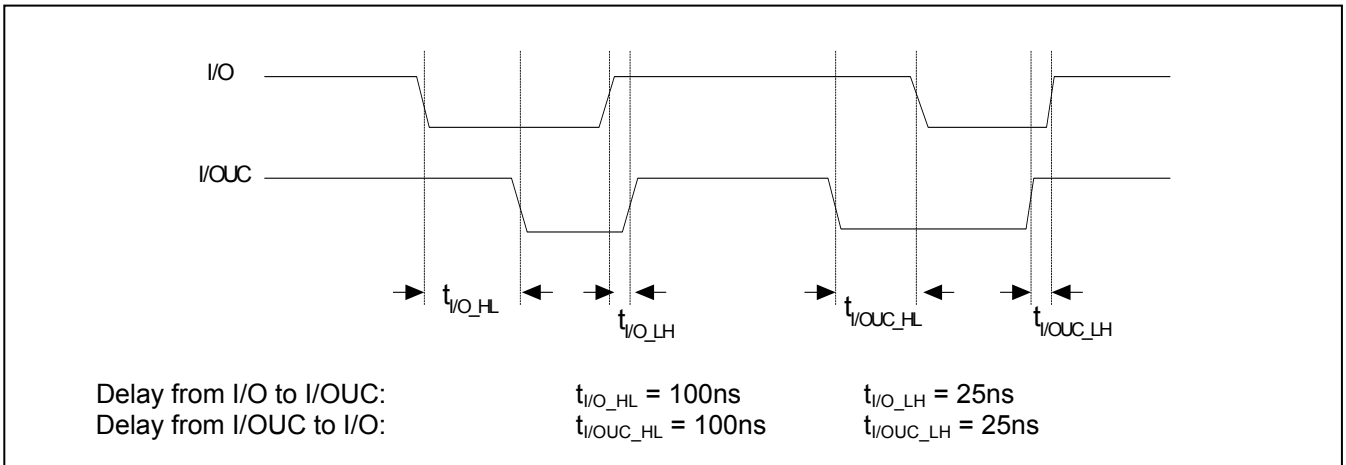


Figure 9: I/O - I/OUC Delays - Timing Diagram

### 4 Equivalent Circuits

This section provides illustrations of circuits equivalent to those described in the pinout section.

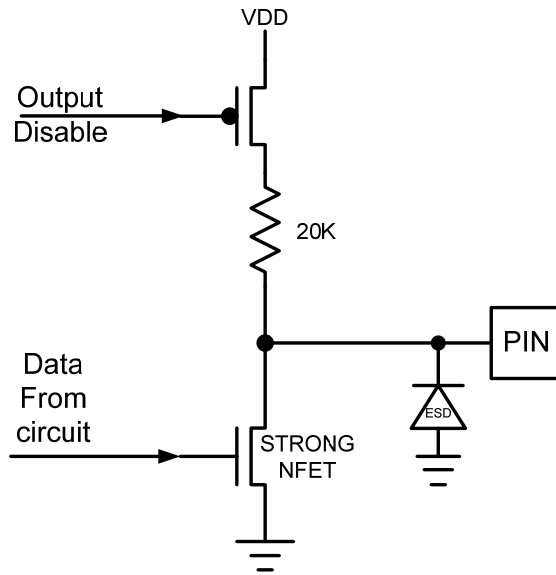


Figure 10: Open Drain type –  $\overline{\text{OFF}}$

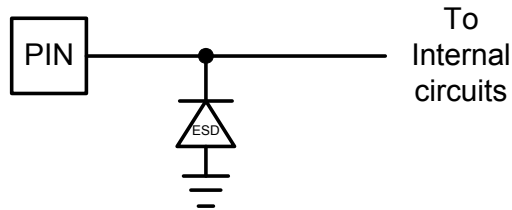


Figure 11: Power Input/Output Circuit,  $V_{DD}$ ,  $V_{PC}$ ,  $V_{CC}$

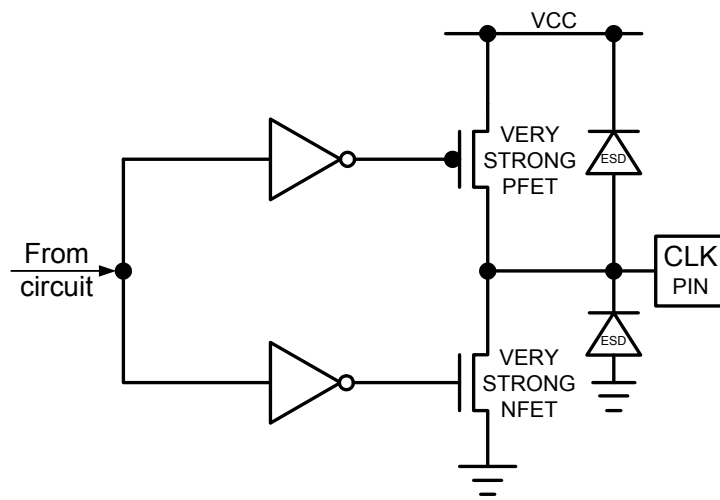


Figure 12: Type 5 – Smart Card CLK Driver Circuit

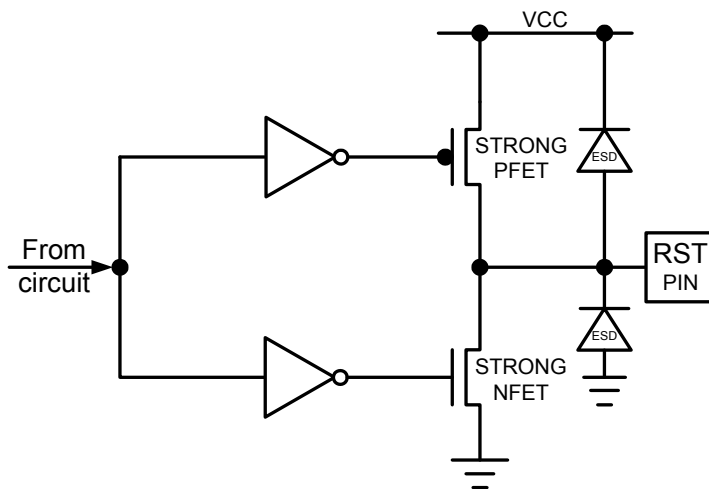


Figure 13: Type 6 – Smart Card RST Driver Circuit

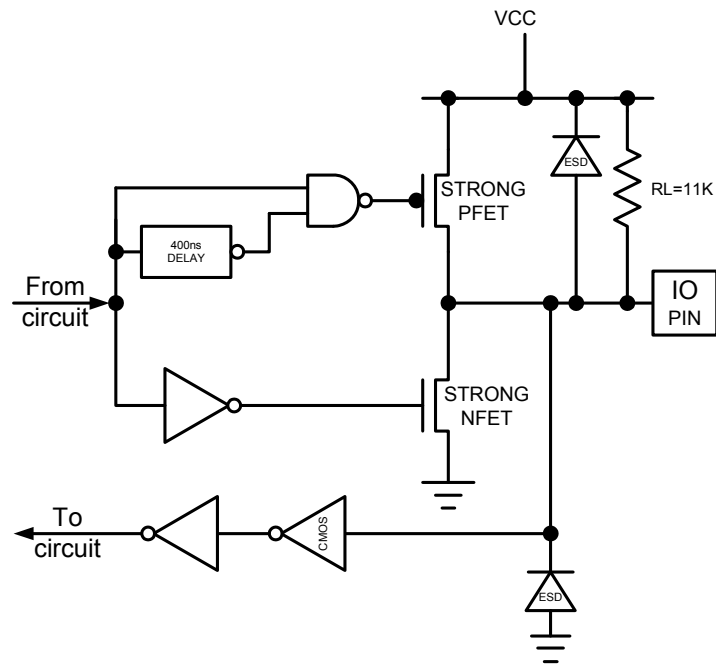


Figure 14: Type 7A – Smart Card IO Interface Circuit

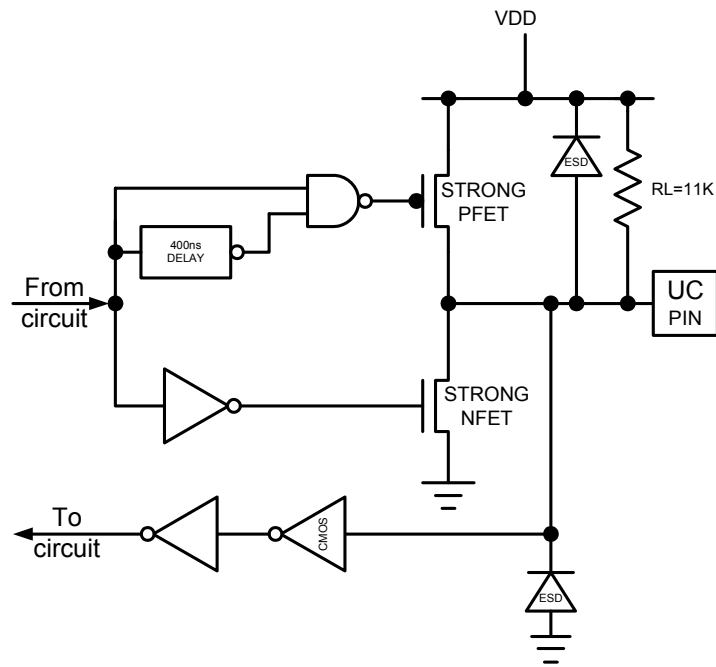
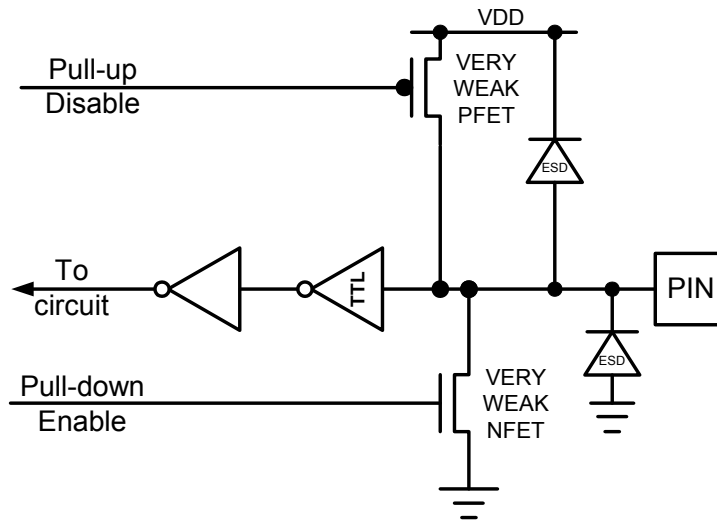


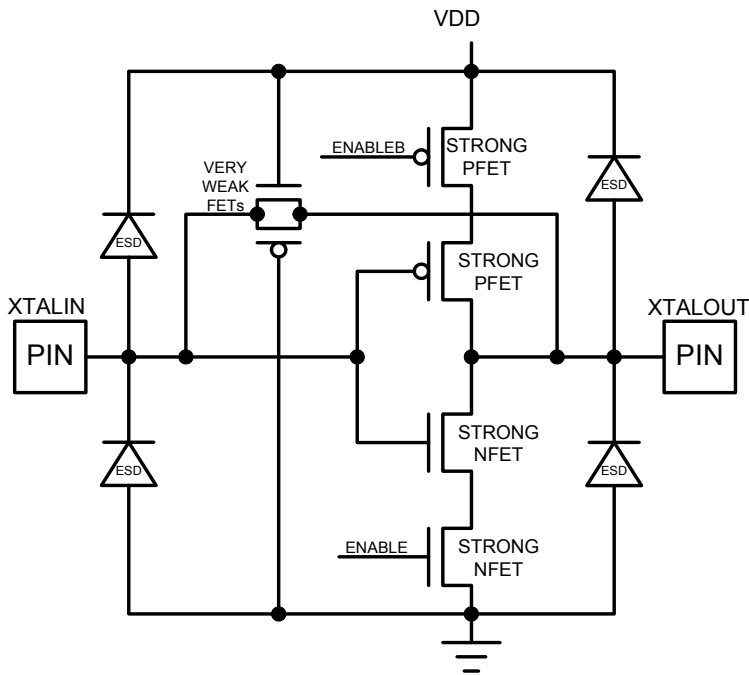
Figure 15: Type 7B – Smart Card IOUC Interface Circuit





Note: Pins  $\overline{\text{CMDVCC5}}$ ,  $\overline{\text{CMDVCC3}}$ , CLKDIV1 and CLKDIV2 have the pull-up enabled.  
 Pins RSTIN, CLKIN, PRES have the pull-down enabled.

**Figure 16: Type 8 – General Input Circuit**



**Figure 17: Oscillator Circuit**

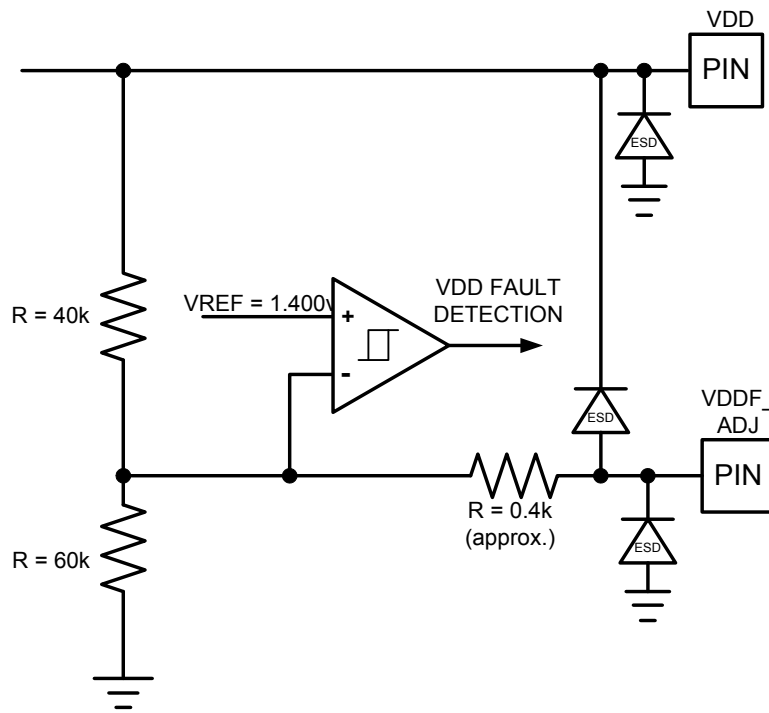


Figure 18: VDD<sub>FLT\_ADJ</sub>

### 5 Mechanical Drawing

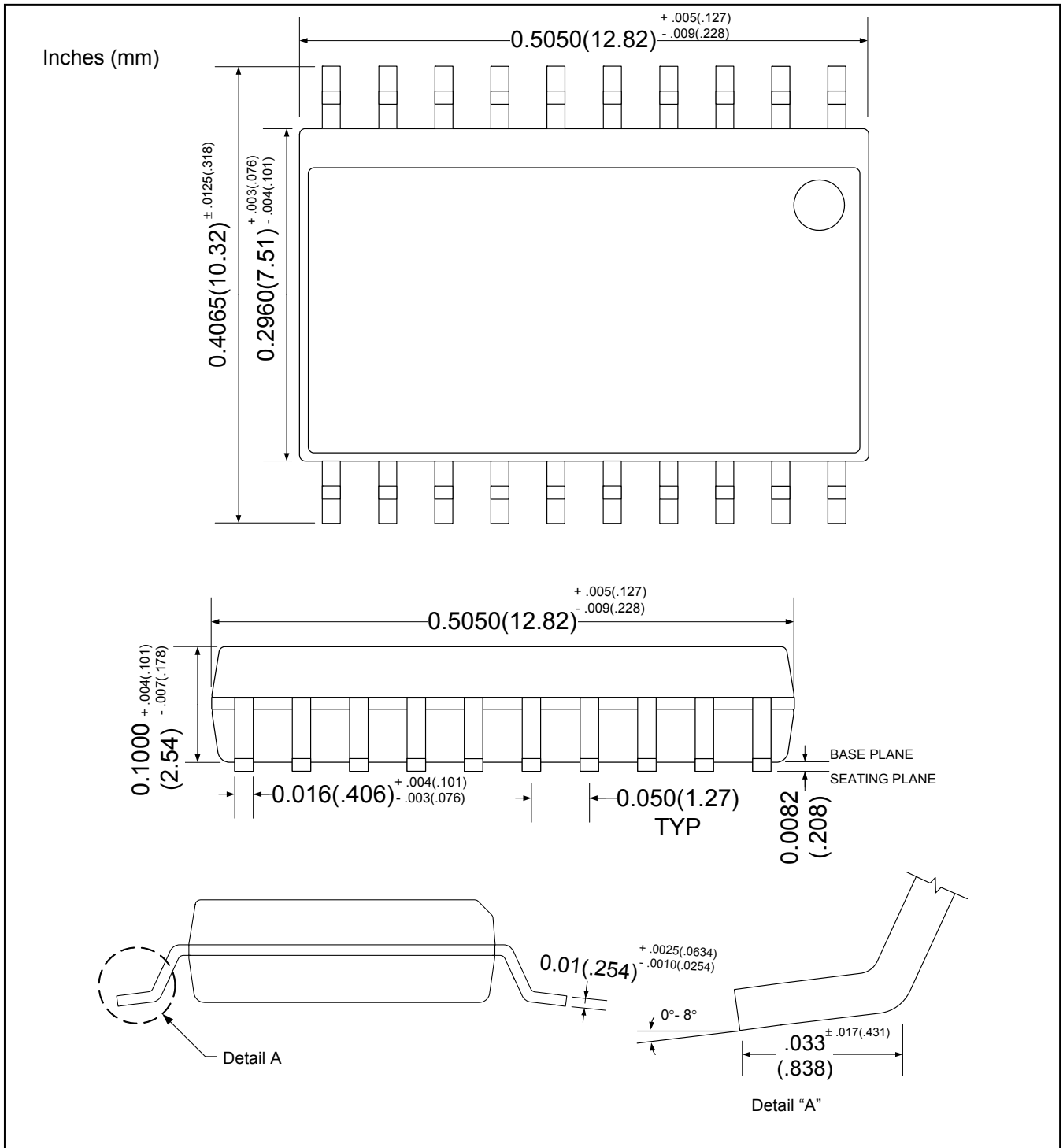


Figure 19: Mechanical Drawing 20-Pin SO Package

## 6 Ordering Information

Table 10 lists the order numbers and packaging marks used to identify 73S8014RT products.

**Table 10: Order Numbers and Packaging Marks**

Part Description	Order Number	Packaging Mark
73S8014RT 20-pin Lead-Free	73S8014RT-IL/F	73S8014RT
73S8014RT 20-pin Lead-Free Tape / Reel	73S8014RT-ILR/F	73S8014RT

## 7 Related Documentation

The following 73S8014RT document is available from Teridian Semiconductor Corporation:

*73S8014R/RN/RT 20SO Demo Board User Manual*

## 8 Contact Information

For more information about Teridian Semiconductor products or to check the availability of the 73S8014RT, contact us at:

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Email: [scr.support@teridian.com](mailto:scr.support@teridian.com)

For a complete list of worldwide sales offices, go to <http://www.teridian.com>.

## Revision History

Revision	Date	Description
1.0	12/12/2008	First publication.

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